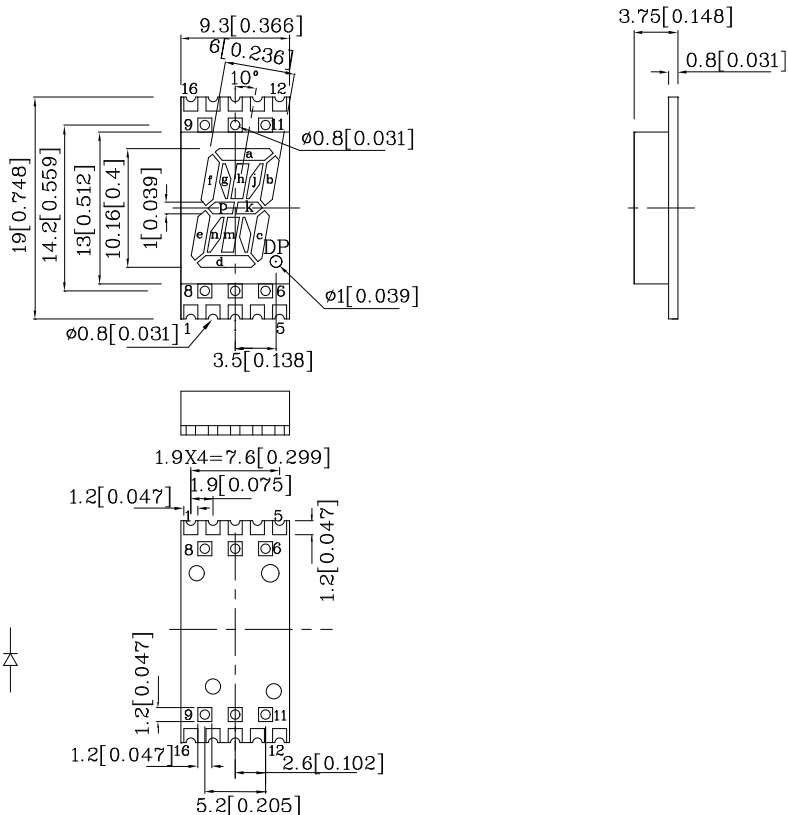
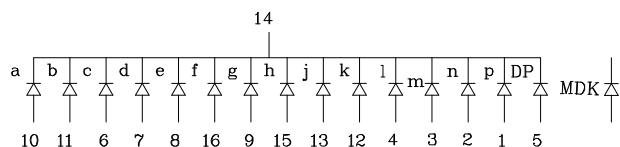


Features

- 0.4 INCH CHARACTER HEIGHT.
- LOW CURRENT OPERATION.
- HIGH CONTRAST AND LIGHT OUTPUT.
- CATEGORIZED FOR LUMINOUS INTENSITY.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE :400PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



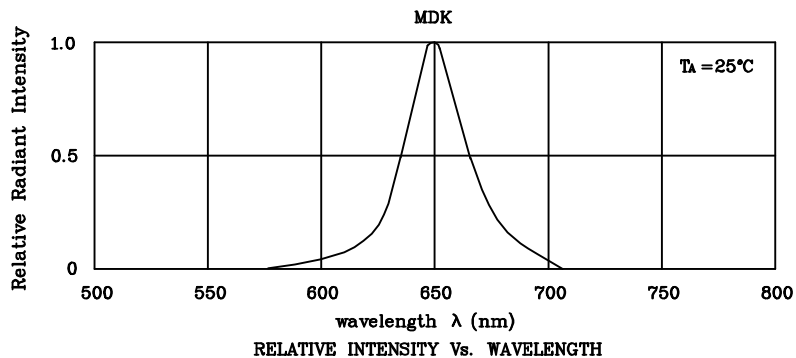
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
- 3.Specifications are subject to change without notice.
- 4.The gap between the reflector and PCB shall not exceed 0.25mm.

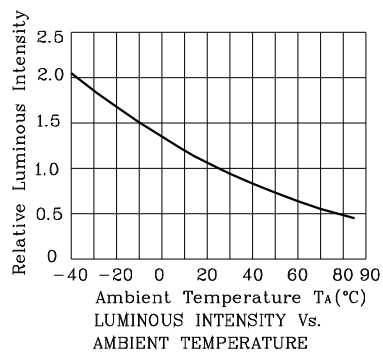
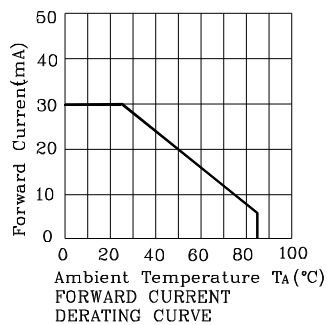
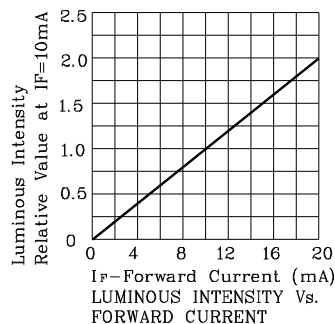
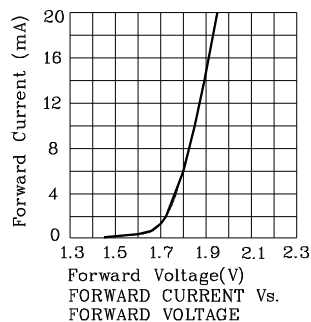
Absolute Maximum Ratings (TA=25°C)		MDK (InGaAlP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	185	mA
Power Dissipation	P _T	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

Operating Characteristics (TA=25°C)		MDK (InGaAlP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	1.85	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength Of Peak Emission (Typ.) (I _F =10mA)	λ P	650	nm
Wavelength Of Dominant Emission (Typ.) (I _F =10mA)	λ D	635	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	28	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd	Wavelength nm λ P	Description
			min.	typ.	
ZFAMDK10C	Red	InGaAlP	4700	22790	650 Common Cathode, Rt. Hand Decimal
Published Date : MAR 03, 2008 Drawing No : SDSA5404 V2 Checked : Shin Chi P.1/4					



❖ **MDK**



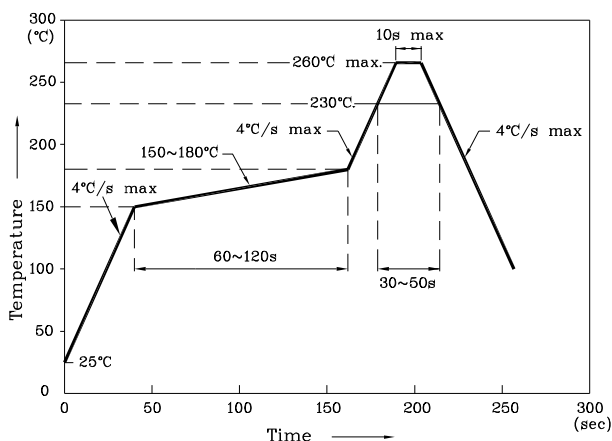
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

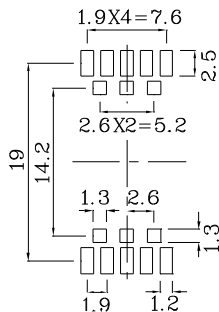
Reflow Soldering Profile For Lead-free SMT Process.



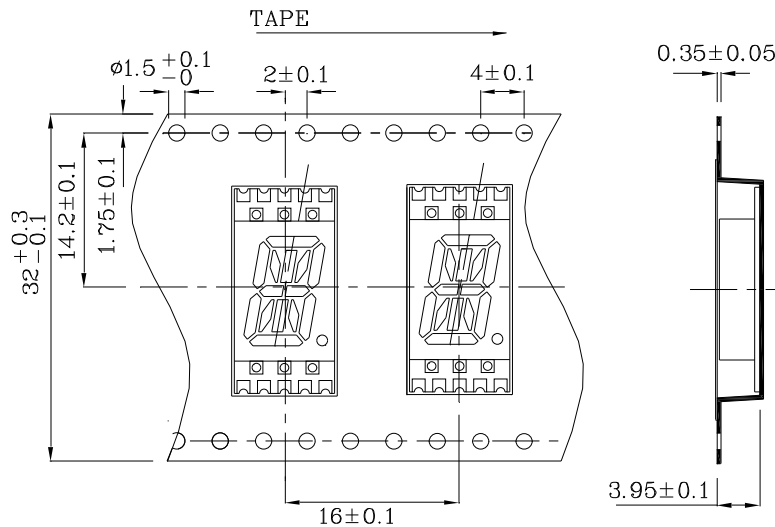
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C~260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ **Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)**



❖ **Tape Specification (Units : mm)**



PACKING & LABEL SPECIFICATIONS ZFAMDK10C

